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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/073,316	02/13/2002	Hideo Nunokawa	020101	5321
23850	7590	06/19/2003		
ARMSTRONG, WESTERMAN & HATTORI, LLP 1725 K STREET, NW SUITE 1000 WASHINGTON, DC 20006			EXAMINER	
			VU, QUANG D	
			ART UNIT	PAPER NUMBER
			2811	

DATE MAILED: 06/19/2003

Please find below and/or attached an Office communication concerning this application or proceeding.

<b>Office Action Summary</b>	Application No.	Applicant(s)
	10/073,316	NUNOKAWA, HIDEO
	Examiner Quang D Vu	Art Unit 2811

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

#### Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133).
- Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

#### Status

1) Responsive to communication(s) filed on amendment filed on 04/08/03.

2a) This action is FINAL.                    2b) This action is non-final.

3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

#### Disposition of Claims

4) Claim(s) 2-17 is/are pending in the application.

4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.

5) Claim(s) \_\_\_\_\_ is/are allowed.

6) Claim(s) 2-17 is/are rejected.

7) Claim(s) \_\_\_\_\_ is/are objected to.

8) Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

#### Application Papers

9) The specification is objected to by the Examiner.

10) The drawing(s) filed on \_\_\_\_\_ is/are: a) accepted or b) objected to by the Examiner.

Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).

11) The proposed drawing correction filed on \_\_\_\_\_ is: a) approved b) disapproved by the Examiner.

If approved, corrected drawings are required in reply to this Office action.

12) The oath or declaration is objected to by the Examiner.

#### Priority under 35 U.S.C. §§ 119 and 120

13) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).

a) All b) Some \* c) None of:

1. Certified copies of the priority documents have been received.
2. Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

14) Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).

a) The translation of the foreign language provisional application has been received.

15) Acknowledgment is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121.

#### Attachments(s)

1) Notice of References Cited (PTO-892)

2) Notice of Draftsperson's Patent Drawing Review (PTO-948)

3) Information Disclosure Statement(s) (PTO-1449) Paper No(s) \_\_\_\_\_.

4) Interview Summary (PTO-413) Paper No(s) \_\_\_\_\_.

5) Notice of Informal Patent Application (PTO-152)

6) Other: \_\_\_\_\_

## DETAILED ACTION

### *Specification*

The specification is objected to as failing to provide proper antecedent basis for the claimed subject matter. See 37 CFR 1.75(d)(1) and MPEP § 608.01(o). Correction of the following is required:

The specification never discloses an inductor connected to at least one of the power line and the ground line is formed by connecting the fourth electrode pad of the condenser chip and the third electrode pad of the semiconductor chip by a bonding wire as claimed in claim 7.

The specification never discloses an inductor connected to at least one of the power line and the ground line is formed by connecting the first electrode pad of the first semiconductor chip and the second electrode pad of the second semiconductor chip by a bonding wire as claimed in claim 9.

The specification never discloses an inductor connected to at least one of the power line and the ground line is formed by connecting the fourth electrode pad of the condenser chip and the third electrode pad of the semiconductor chip by a bonding wire as claimed in claim 16.

### *Claim Rejections - 35 USC § 112*

1. The following is a quotation of the second paragraph of 35 U.S.C. 112:

The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.

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2. Claims 2-8, 11-17 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

Claim 2, in line 8, the phrase "...condenser chip has a plurality of condensers corresponding to the circuit blocks" is unclear as to what is the relationship between the condensers and the circuit blocks.

Claim 2, in lines 3 and 7, the phrase "...a semiconductor chip having a circuit block...wherein a plurality of circuit blocks are formed in the semiconductor chip..." is unclear whether the circuit block is different from the plurality of circuit blocks.

Claim 2, in lines 4 and 8, the phrase "...a condenser chip in which a noise reduction condenser...condenser chip has a plurality of condensers..." is unclear whether the condenser is different from the plurality of condensers.

Claim 3, in line 8, the phrase "...condenser chip has a plurality of condensers corresponding to the circuit blocks" is unclear as to what is the relationship between the condensers and the circuit blocks.

Claim 3, in lines 3 and 7, the phrase "...a semiconductor chip having a circuit block...wherein a plurality of circuit blocks are formed in the semiconductor chip..." is unclear whether the circuit block is different from the plurality of circuit blocks.

Claim 3, in lines 4 and 8, the phrase "...a condenser chip in which a noise reduction condenser...a plurality of condensers..." is unclear whether the condenser chip is different from the plurality of condensers.  
*chips*

Claim 4, in lines 7-8, the phrase “...the semiconductor chip has a first power supply pad provided on a connecting line extending from one of the power supply line and the ground line to the circuit block” is unclear as to how the power supply pad provided on a connecting line extending from one of the power supply line and the ground line to the circuit block. The specification discloses the semiconductor chip (1) has a first power supply pad (1a) electrically connected from one of the power line (8) and the ground line (9) to the circuit block. The specification never discloses the semiconductor chip has a first power supply pad provided on a connecting line extending from one of the power supply line and the ground line to the circuit block.

Claim 4, in line 9, the phrase “...condenser chip has a second electrode pad...” is unclear as to where is the first electrode pad of the condenser chip.

Claim 5, in lines 7-8, the phrase “...the semiconductor chip has a first power supply pad provided on a connecting line extending from one of the power supply line and the ground line to the circuit block” is unclear as to how the power supply pad provided on a connecting line extending from one of the power supply line and the ground line to the circuit block. The specification discloses the semiconductor chip (1) has a first power supply pad (1a) electrically connected from one of the power line (8) and the ground line (9) to the circuit block. The specification never discloses the semiconductor chip has a first power supply pad provided on a connecting line extending from one of the power supply line and the ground line to the circuit block.

Claim 5, in line 9, the phrase “...condenser chip has a second electrode pad...” is unclear as to where is the first electrode pad of the condenser chip.

Claim 7, in line 2, the phrase "...the semiconductor chip has a third electrode pad..." is unclear as to where is the second electrode pad of the semiconductor chip.

Claim 7, in line 4, the phrase "...the condenser chip has a fourth electrode pad..." is unclear as to where are the first, second and third electrode pads of the condenser chip.

Claim 8, in lines 1-3, the phrase "...a plurality of the fourth electrode pads of the condenser chip are provided and a plurality of the third electrode pads of the semiconductor chip are provided..." is unclear as to where are the first, second and third electrode pads of the condenser chip and where is the second electrode pad of the semiconductor chip.

Claim 11, in lines 6-7, the phrase "...the circuit block is connect to the condenser chip on a connecting line extending from one of the ring shaped power supply line and grounding line to the circuit block" is unclear as to how the circuit block is connected to the condenser chip on a connecting line. The specification discloses the electrode pads (1b) are provided on a connecting line which extends from a power supply line (8) to the circuit region block A (circuit region C) and on a connecting line which extends from a ground line 9 to the circuit region block A (circuit region C) (page 10, lines 22-27). The specification never discloses the circuit block is connect to the condenser chip on a connecting line extending from one of the ring shaped power supply line and grounding line to the circuit block.

Claim 12, in lines 6-7, the phrase "...the circuit block is connected to the condenser chip on a connecting line extending from one of the ring shaped power supply line and grounding line to the circuit block" is unclear as to how the circuit block is connected to the condenser chip on a connecting line. The specification discloses the electrode pads (1b) are provided on a connecting line which extends from a power supply line (8) to the circuit region block A (circuit region C)

and on a connecting line which extends from a ground line 9 to the circuit region block A (circuit region C) (page 10, lines 22-27). The specification never discloses the circuit block is connected to the condenser chip on a connecting line extending from one of the ring shaped power supply line and grounding line to the circuit block.

Claim 16, in line 2, the phrase "...the semiconductor chip has a third electrode pad..." is unclear as to where is the second electrode pad of the semiconductor chip.

Claim 16, in line 4, the phrase "...the condenser chip has a fourth electrode pad..." is unclear as to where are the first, second, and third electrode pads of the condenser chip.

Claim 17, in lines 1-3, the phrase "...a plurality of the fourth electrode pads of the condenser chip are provided and a plurality of the third electrode pads of the semiconductor chip are provided..." is unclear as to where are the first, second and third electrode pads of the condenser chip and where is the second electrode pad of the semiconductor chip.

#### *Allowable Subject Matter*

3. Claims 9-10 are allowed.

4. The following is a statement of reasons for the indication of allowable subject matter:

The most closely related art, US Patent No. 5,677,570 to Kondoh et al. do not anticipate or render the claimed invention such as a first semiconductor chip having a circuit block, a power supply line and a ground line; and a second semiconductor chip stacked on the first semiconductor chip, wherein the first semiconductor chip has a first electrode pad separated from a circuit formed within the first semiconductor chip.

***Conclusion***

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Quang D Vu whose telephone number is 703-305-3826. The examiner can normally be reached on Monday-Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Tom Thomas can be reached on 703-308-2772. The fax phone numbers for the organization where this application or proceeding is assigned are 703-308-7722 for regular communications and 703-308-7722 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is 703-308-0956.

qv  
June 16, 2003

Steven Loh  
Primary Examiner  
*Steven Loh*